



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-05-25
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB18N60M2	TLD2*MQ6GB62	A	3068	2017-05-25
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-9.15-4.5	2	gull wing	
Comment	D2PAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.13	Die back side metal - Leadframe metal	96
Lead	7.42	Soft solder	5377

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TLD2*MQ6G862					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	8.507	mg	supplier	die	Silicon (Si)	7440-21-3		8.169	mg	960268	5920
				supplier	metallization	Aluminium (Al)	7429-90-5		0.162	mg	19044	117
				supplier	Passivation	Silicon Nitride	12033-89-5		0.039	mg	4584	28
				supplier	Passivation	Silicon Oxide	7631-86-9		0.057	mg	6700	41
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	470	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.056	mg	6583	41
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.020	mg	2351	14
				supplier	alloy	Copper (Cu)	7440-50-8		777.537	mg	998594	563433
				supplier	alloy	Iron (Fe)	7439-89-6		0.358	mg	459	259
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.654	mg	840	474
Leadframe	Copper & its alloys	778.632	mg	supplier	metallization	Nickel (Ni)	7440-02-0		0.077	mg	99	56
				supplier	metallization	Phosphorus (P)	12185-10-3		0.006	mg	8	4
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	7.420	mg	955078	5377
				supplier	solder	Silver (Ag)	7440-22-4		0.194	mg	24971	141
				supplier	solder	Tin (Sn)	7440-31-5		0.155	mg	19951	112
				supplier	wire	Aluminium (Al)	7429-90-5		0.771	mg	996124	559
Soft solder	Solder	7.769	mg	JIG - R	solder	Magnesium (Mg)	7439-95-4		0.003	mg	3876	2
				supplier	solder	Silica, vitreous	60676-86-0		509.100	mg	874999	368913
				supplier	solder	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		23.273	mg	40000	16864
				supplier	solder	Epoxy Resin	25068-38-6		17.455	mg	30000	12649
				supplier	solder	phenol resin	29690-82-2		29.092	mg	50001	21081
Bonding wires	Other inorganic materials	0.774	mg	supplier	wire	Carbon black	1333-86-4		2.909	mg	5000	2108
				supplier	wire	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804
				supplier	wire	Aluminium (Al)	7429-90-5		0.771	mg	996124	559
Encapsulation	Other Organic Materials	581.829	mg	supplier	mold compound	Silica, vitreous	60676-86-0		509.100	mg	874999	368913
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		23.273	mg	40000	16864
				supplier	mold compound	Epoxy Resin	25068-38-6		17.455	mg	30000	12649
				supplier	mold compound	phenol resin	29690-82-2		29.092	mg	50001	21081
Connections coating	Solder	2.489	mg	supplier	mold compound	Carbon black	1333-86-4		2.909	mg	5000	2108
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804